



General Description

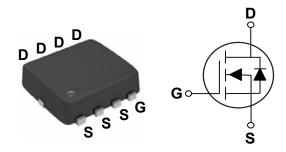
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
30V	8.5 mΩ	48 A

Features

- $R_{DS(ON)} \leq 8.5 m\Omega@V_{GS} = 10V$
- · Improved dv/dt capability
- · Fast switching
- · Green Device Available

PPAK3X3 Pin Configuration



Applications

- · MB / VGA / Vcore
- POL Applications
- · SMPS 2nd SR

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Parameter	Rating				
V _{DS}	Drain-Source Voltage	30	V			
V_{GS}	Gate-Source Voltage	±20	V			
1	Drain Current - Continuous (T _C =25°C)	48	Α			
I _D	Drain Current - Continuous (T _C =100°C)	30	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	192	Α			
EAS	Single Pulse Avalanche Energy (NOTE 2)	31	mJ			
IAS	Single Pulse Avalanche Current (NOTE 2)	25	Α			
Power Dissipation (T _C =25°C)		35	W			
I D	Power Dissipation - Derate above 25°C	0.28	W/°C			
T_J	Operating Junction Temperature Range	-50 to 150	°C			
T _{STG}	Storage Temperature Range	-50 to 150	°C			
Marking Code		NC8P5 , DC3908				

Thermal Characteristics					
Symbol Parameter Typ. Ma		Max	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		3.6	°C/W	





Electrical Characteristics (T_{.1}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30			V
I _{DSS} D	IDrain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_{J} =25°C			1	uA
		V_{DS} =24V , V_{GS} =0V , T_{J} =125 $^{\circ}$ C			10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =15A			8.5	mΩ
DS(ON)	(NOTE 3)	V_{GS} =4.5V , I_D =8A			13	11152
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2	1.6	2.5	V
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			23.2		
Q_{gs}	Gate-Source Charge	V_{DS} =15V , V_{GS} =10V , I_{D} =1A		3.2		nC
Q_{gd}	Gate-Drain Charge			3.7		
$T_{d(on)}$	Turn-On Delay Time	V_{DD} =10V , V_{GS} =10V , R_{GEN} =2.7 Ω , I_{D} =30A		7		
T _r	Rise Time			76.6		nS
$T_{d(off)}$	Turn-Off Delay Time			27.1		110
T_f	Fall Time			52.6		
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , F=1MHz		1180		
C _{oss}	Output Capacitance			177		pF
C _{rss}	Reverse Transfer Capacitance			132		
Rg	Gate resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		3.2		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V,Force Current			48	Α
I _{SM}	Pulsed Source Current (NOTE 3)				192	Α
V_{SD}	Diode Forward Voltage (NOTE 3)	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

NOTES

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =25A, R_{G} =25 Ω , Starting T_{J} =25 $^{\circ}$ C.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.





Characteristics Curves

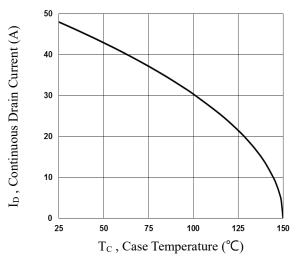


Fig.1 Continuous Drain Current vs. Tc

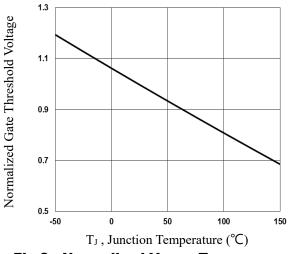


Fig.3 Normalized V_{th} vs. T_J

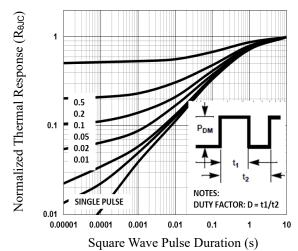


Fig.5 Normalized Transient Impedance

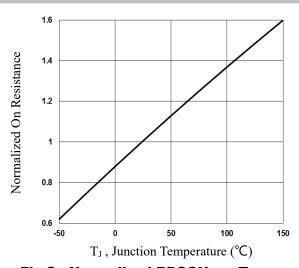


Fig.2 Normalized RDSON vs. T_J

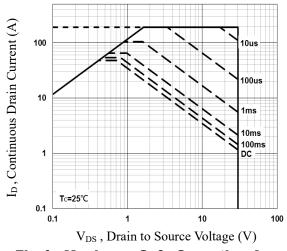


Fig.4 Maximum Safe Operation Area

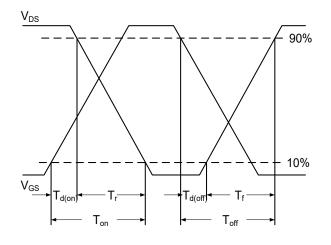


Fig.6 Switching Time Waveform





Characteristics Curves

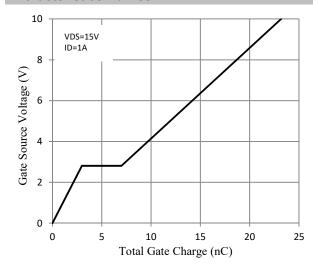


FIG. 7 Gate Charge Characteristics

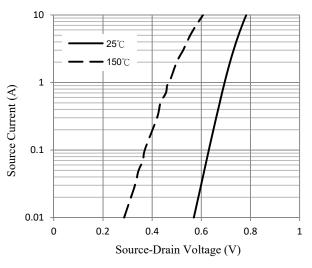


FIG. 9 Diode Forward Characteristics

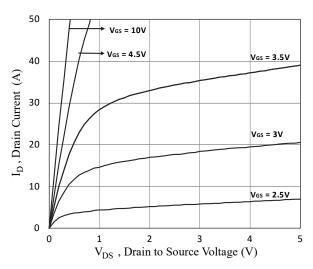


FIG. 11 Output Characteristics

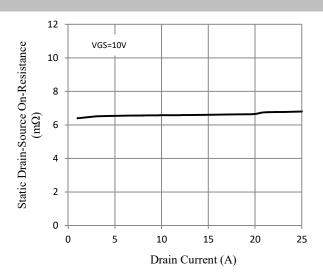


FIG. 8 RDSON vs I_D

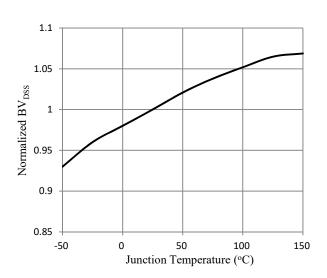


FIG. 10 Normalized BV_{DSS} vs T_J

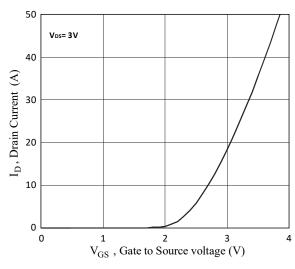
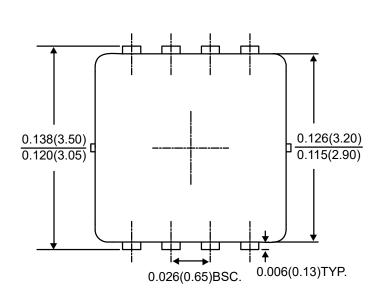


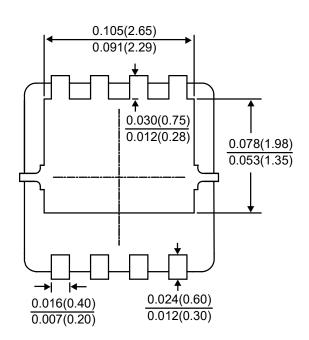
FIG. 12 Transfer Characteristics

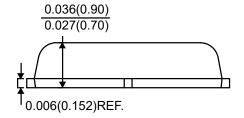


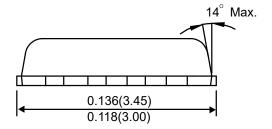


Package Outline Dimensions









PPAK3X3

Dimensions in inches and (millimeters)





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